



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-09-13
Company Unique ID	NL 008751171801		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Floriana SAN BIAGIO	Representative Title	AMS MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	9F17*L750UA6	A	Z8GA	2018-09-13
Amount	UoM	Unit type	ST ECOPACK Grade	
1025	mg	Each	ECOPACK® 2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
Not Applicable	Not Applicable	Not Applicable		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DIP	17X19.18X6.35	16	Through-hole	
Comment	17 PDIP 16 .3 Cu .25 STD; MDF valid for SG3524N			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	9F17*L750UA6				6000001.0	1000000.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	2.947	mg	supplier	die	Silicon (Si)	7440-21-3		2.853	mg	968103	2783
				supplier	metallization	Aluminium (Al)	7429-90-5		0.036	mg	12216	35
				supplier	Passivation	Silicon Nitride	12033-89-5		0.013	mg	4411	13
				supplier	Passivation	Silicon Oxide	7631-86-9		0.017	mg	5769	17
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.002	mg	679	2
				supplier	back side metallization	Gold (Au)	7440-57-5		0.006	mg	2036	6
Leadframe	M-004 Copper and its alloys	572.266	mg	supplier	back side metallization	Nickel (Ni)	7440-02-0		0.020	mg	6787	20
				supplier	alloy	Iron Phosphide (Fe2P)	1310-43-6		0.486	mg	849	474
				supplier	alloy	Iron (Fe)	7439-89-6		13.448	mg	23500	33120
				supplier	alloy	Copper (Cu)	7440-50-8		557.560	mg	974302	543961
				supplier	alloy	Zinc (Zn)	7440-66-6		0.715	mg	1249	698
				supplier	metallization	Silver (Ag)	7440-22-4		0.057	mg	100	56
Die attach	M-015 Other organic materials	0.738	mg	supplier	glue	Silver (Ag)	7440-22-4		0.528	mg	715447	515
				supplier	glue	Epoxy Resin	25068-38-6		0.111	mg	150407	108
				supplier	glue	2,6-Diglycidyl phenyl allyl ether oligomer	Proprietary		0.055	mg	74526	54
				supplier	glue	Epoxy resin modifier	Proprietary		0.022	mg	29810	21
				supplier	glue	Amine	Proprietary		0.022	mg	29810	21
Bonding wires	M-008 Precious metals	0.119	mg	supplier	wire	Gold (Au)	7440-57-5		0.119	mg	1000000	116
Encapsulation	M-015 Other organic materials	436.015	mg	supplier	Molding compound	Silica (Amorphous)	60676-86-0		333.522	mg	764932	325387
				supplier	Molding compound	Epoxy resin	29690-82-2		43.614	mg	100029	42550
				supplier	Molding compound	Phenol resin	9003-35-4		13.084	mg	30008	12765
				supplier	Molding compound	Metal Hydroxide	Proprietary		43.614	mg	100029	42550
				supplier	Molding compound	Carbon black	1333-86-4		2.181	mg	5002	2128
connections coating	M-011 Other inorganic materials	12.915	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		12.915	mg	1000000	12600